



Material Content Data Sheet



Sales Product Name				IPG20N10S4L-22A		Issued		9. January 2019	
MA#				MA001094672					
Package				PG-TDSON-8-10		Weight*		100.30 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	1.592	1.59	1.59	15871	15871	
chip_2	inorganic material	silicon	7440-21-3	1.592	1.59	1.59	15871	15871	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		131		
	non noble metal	iron	7439-89-6	0.044	0.04		436		
	non noble metal	copper	7440-50-8	43.681	43.55	43.60	435501	436068	
	non noble metal	aluminium	7429-90-5	0.713	0.71	0.71	7112	7112	
wire	non noble metal	aluminium	7429-90-5	0.713	0.71	0.71	7112	7112	
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		887		
	plastics	epoxy resin	-	6.316	6.30		62966		
	inorganic material	silicondioxide	60676-86-0	38.071	37.96	44.35	379568	443421	
leadfinish	non noble metal	tin	7440-31-5	1.396	1.39	1.39	13922	13922	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		14		
	non noble metal	nickel	7440-02-0	0.603	0.60	0.60	6013	6027	
solder	non noble metal	tin	7440-31-5	0.070	0.07		695		
	noble metal	silver	7440-22-4	0.087	0.09		869		
	non noble metal	lead	7439-92-1	3.330	3.32	3.48	33202	34766	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		8		
	non noble metal	iron	7439-89-6	0.003	0.00		27		
	non noble metal	copper	7440-50-8	2.699	2.69	2.69	26907	26942	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com